

## FEATURES

- Member of the Texas Instruments Widebus+™ Family
- Optimized for 1.8-V Operation and Is 3.6-V I/O Tolerant to Support Mixed-Mode Signal Operation
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Sub-1-V Operable
- Max t<sub>pd</sub> of 2 ns at 1.8 V
- Low Power Consumption, 40-μA Max I<sub>CC</sub>
- ±8-mA Output Drive at 1.8 V
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## DESCRIPTION/ORDERING INFORMATION

This 32-bit noninverting bus transceiver is operational at 0.8-V to 2.7-V V<sub>CC</sub>, but is designed specifically for 1.65-V to 1.95-V V<sub>CC</sub> operation.

The SN74AUC32245 is designed for asynchronous communication between data buses. The control-function implementation minimizes external timing requirements.

This device can be used as four 8-bit transceivers, two 16-bit transceivers, or one 32-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ( $\overline{OE}$ ) input can be used to disable the device so that the buses are effectively isolated.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

## ORDERING INFORMATION

T <sub>A</sub>	PACKAGE <sup>(1)</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	LFBGA – GKE	Tape and reel	SN74AUC32245GKER	MM245

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



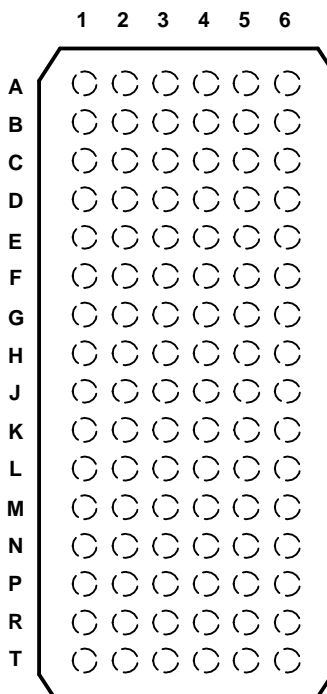
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**SN74AUC32245**  
**32-BIT BUS TRANSCEIVER**  
**WITH 3-STATE OUTPUTS**

SCES410C—AUGUST 2002—REVISED MARCH 2005

**GKE PACKAGE**  
**(TOP VIEW)**



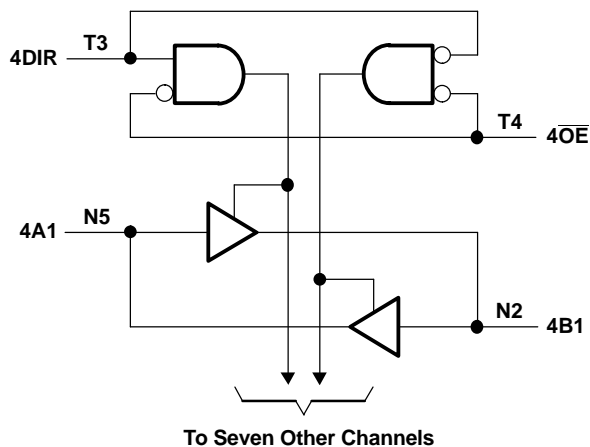
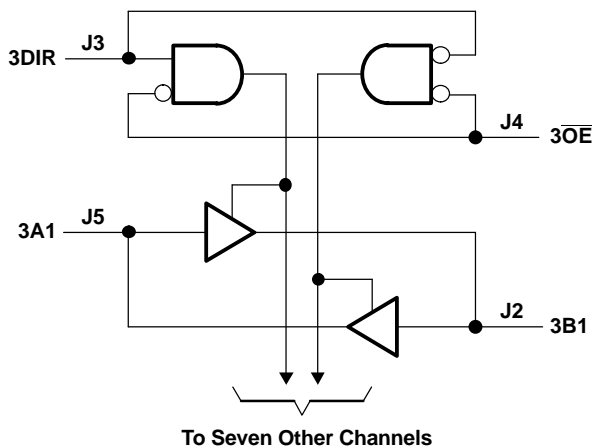
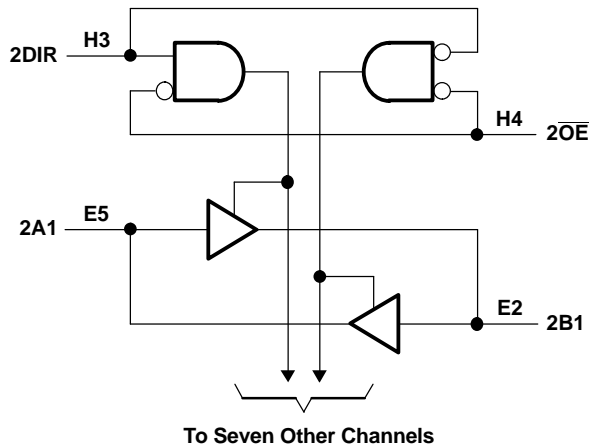
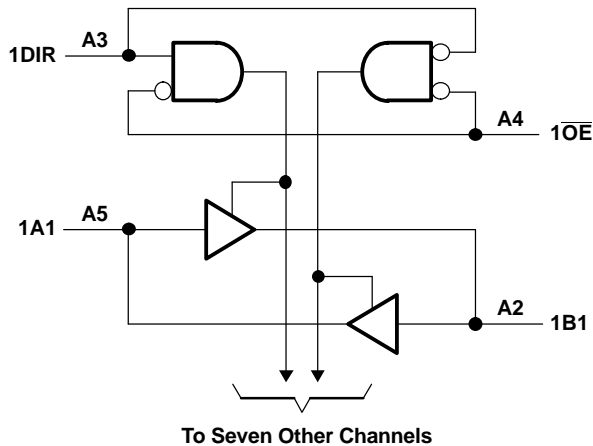
**TERMINAL ASSIGNMENTS**

	1	2	3	4	5	6
<b>A</b>	1B2	1B1	1DIR	1 $\overline{OE}$	1A1	1A2
<b>B</b>	1B4	1B3	GND	GND	1A3	1A4
<b>C</b>	1B6	1B5	V <sub>CC</sub>	V <sub>CC</sub>	1A5	1A6
<b>D</b>	1B8	1B7	GND	GND	1A7	1A8
<b>E</b>	2B2	2B1	GND	GND	2A1	2A2
<b>F</b>	2B4	2B3	V <sub>CC</sub>	V <sub>CC</sub>	2A3	2A4
<b>G</b>	2B6	2B5	GND	GND	2A5	2A6
<b>H</b>	2B7	2B8	2DIR	2 $\overline{OE}$	2A8	2A7
<b>J</b>	3B2	3B1	3DIR	3 $\overline{OE}$	3A1	3A2
<b>K</b>	3B4	3B3	GND	GND	3A3	3A4
<b>L</b>	3B6	3B5	V <sub>CC</sub>	V <sub>CC</sub>	3A5	3A6
<b>M</b>	3B8	3B7	GND	GND	3A7	3A8
<b>N</b>	4B2	4B1	GND	GND	4A1	4A2
<b>P</b>	4B4	4B3	V <sub>CC</sub>	V <sub>CC</sub>	4A3	4A4
<b>R</b>	4B6	4B5	GND	GND	4A5	4A6
<b>T</b>	4B7	4B8	4DIR	4 $\overline{OE}$	4A8	4A7

**FUNCTION TABLE  
(EACH 8-BIT SECTION)**

INPUTS		OPERATION
$\overline{\text{OE}}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

**LOGIC DIAGRAM (POSITIVE LOGIC)**



# SN74AUC32245

## 32-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCES410C–AUGUST 2002–REVISED MARCH 2005

### Absolute Maximum Ratings<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage range	–0.5	3.6	V
$V_I$	Input voltage range <sup>(2)</sup>	–0.5	3.6	V
$V_O$	Voltage range applied to any output in the high-impedance or power-off state <sup>(2)</sup>	–0.5	3.6	V
$V_O$	Output voltage range <sup>(2)</sup>	–0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current		–50	mA
	$V_I < 0$			
$I_{OK}$	Output clamp current		–50	mA
	$V_O < 0$			
$I_O$	Continuous output current		±20	mA
	Continuous current through $V_{CC}$ or GND		±100	mA
$\theta_{JA}$	Package thermal impedance <sup>(3)</sup>		40	°C/W
$T_{stg}$	Storage temperature range	–65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.

### Recommended Operating Conditions<sup>(1)</sup>

		MIN	MAX	UNIT
$V_{CC}$	Supply voltage	0.8	2.7	V
$V_{IH}$	High-level input voltage	$V_{CC} = 0.8$ V	$V_{CC}$	V
		$V_{CC} = 1.1$ V to 1.95 V	$0.65 \times V_{CC}$	
		$V_{CC} = 2.3$ V to 2.7 V	1.7	
$V_{IL}$	Low-level input voltage	$V_{CC} = 0.8$ V	0	V
		$V_{CC} = 1.1$ V to 1.95 V	$0.35 \times V_{CC}$	
		$V_{CC} = 2.3$ V to 2.7 V	0.7	
$V_I$	Input voltage	0	3.6	V
$V_O$	Output voltage	Active state	0	$V_{CC}$
		3-state	0	3.6
$I_{OH}$	High-level output current	$V_{CC} = 0.8$ V	–0.7	mA
		$V_{CC} = 1.1$ V	–3	
		$V_{CC} = 1.4$ V	–5	
		$V_{CC} = 1.65$ V	–8	
		$V_{CC} = 2.3$ V	–9	
$I_{OL}$	Low-level output current	$V_{CC} = 0.8$ V	0.7	mA
		$V_{CC} = 1.1$ V	3	
		$V_{CC} = 1.4$ V	5	
		$V_{CC} = 1.65$ V	8	
		$V_{CC} = 2.3$ V	9	
$\Delta t/\Delta v$	Input transition rise or fall rate		5	ns/V
$T_A$	Operating free-air temperature	–40	85	°C

- (1) All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

## Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> = -100 μA	0.8 V to 2.7 V	V <sub>CC</sub> - 0.1			V
		I <sub>OH</sub> = -0.7 mA	0.8 V	0.55			
		I <sub>OH</sub> = -3 mA	1.1 V	0.8			
		I <sub>OH</sub> = -5 mA	1.4 V	1			
		I <sub>OH</sub> = -8 mA	1.65 V	1.2			
		I <sub>OH</sub> = -9 mA	2.3 V	1.8			
V <sub>OL</sub>		I <sub>OL</sub> = 100 μA	0.8 V to 2.7 V			0.2	V
		I <sub>OL</sub> = 0.7 mA	0.8 V	0.25			
		I <sub>OL</sub> = 3 mA	1.1 V			0.3	
		I <sub>OL</sub> = 5 mA	1.4 V			0.4	
		I <sub>OL</sub> = 8 mA	1.65 V			0.45	
		I <sub>OL</sub> = 9 mA	2.3 V			0.6	
I <sub>I</sub>	All inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	0 to 2.7 V			±5	μA
I <sub>off</sub>		V <sub>I</sub> or V <sub>O</sub> = 2.7 V	0			±10	μA
I <sub>OZ</sub> <sup>(2)</sup>		V <sub>O</sub> = V <sub>CC</sub> or GND	2.7 V			±10	μA
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	0.8 V to 2.7 V			40	μA
C <sub>i</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	2.5 V			3	pF
C <sub>io</sub>		V <sub>O</sub> = V <sub>CC</sub> or GND	2.5 V			7	pF

 (1) All typical values are at T<sub>A</sub> = 25°C.

 (2) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

## Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

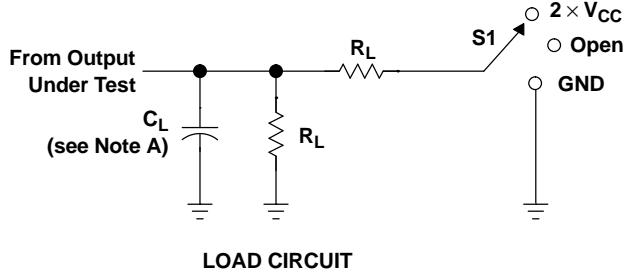
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub> = 1.2 V ± 0.1 V		V <sub>CC</sub> = 1.5 V ± 0.1 V		V <sub>CC</sub> = 1.8 V ± 0.15 V			V <sub>CC</sub> = 2.5 V ± 0.2 V		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	TYP	MAX	MIN	MAX	
t <sub>pd</sub>	A or B	B or A	5.6	0.5	3.1	0.5	2	0.5	1.5	2	0.4	1.9	ns
t <sub>en</sub>	$\overline{OE}$	A or B	10	0.7	4.6	0.7	3.1	0.7	2.1	3.1	0.7	2.6	ns
t <sub>dis</sub>	$\overline{OE}$	A or B	12.8	0.8	6.8	0.8	5	0.8	3.4	4.8	0.5	2.9	ns

## Operating Characteristics

 T<sub>A</sub> = 25°C

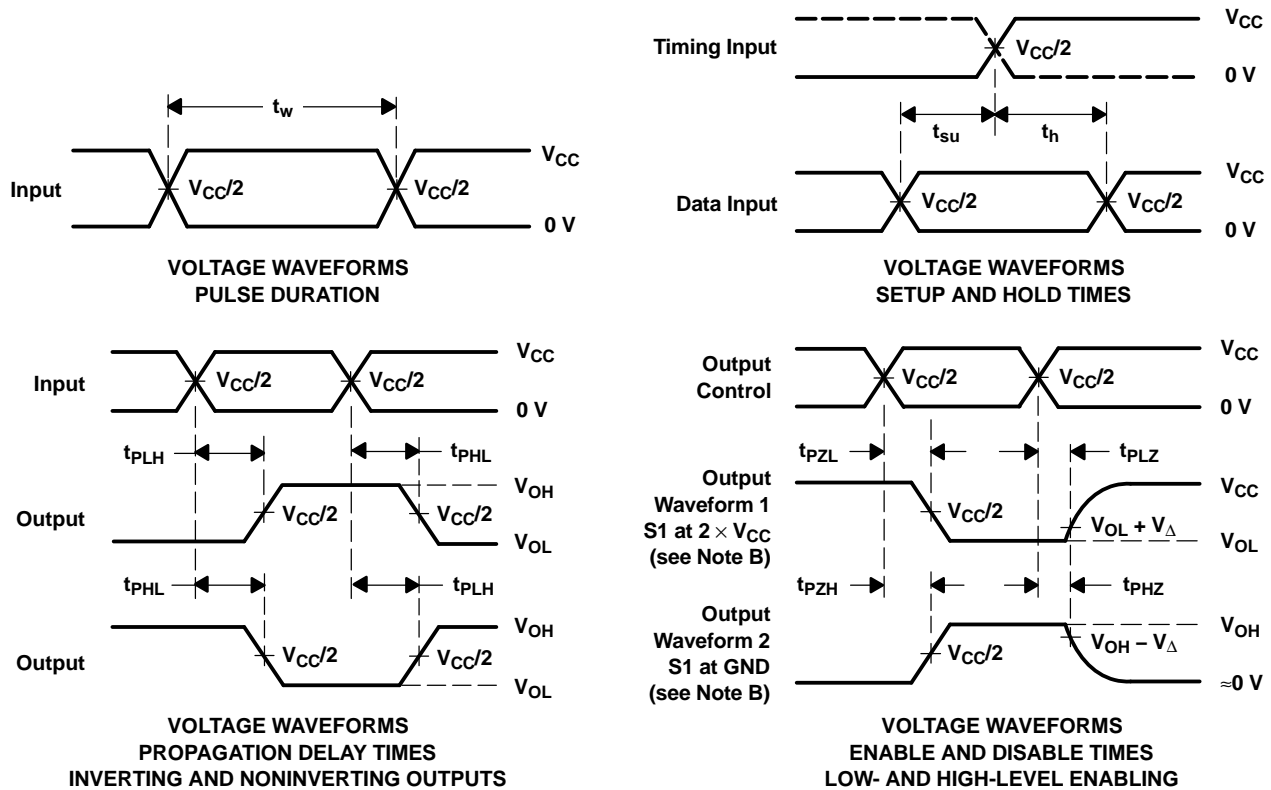
PARAMETER		TEST CONDITIONS	V <sub>CC</sub> = 0.8 V	V <sub>CC</sub> = 1.2 V	V <sub>CC</sub> = 1.5 V	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	UNIT
			TYP	TYP	TYP	TYP	TYP	
C <sub>pd</sub>	Power dissipation capacitance	Outputs enabled f = 10 MHz	22	23	24	25	29	pF
			Outputs disabled	1	1	1	1	

**PARAMETER MEASUREMENT INFORMATION**



TEST	S1
$t_{PLH}/t_{PHL}$	Open
$t_{PLZ}/t_{PZL}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PZH}$	GND

$V_{CC}$	$C_L$	$R_L$	$V_{\Delta}$
0.8 V	15 pF	2 k $\Omega$	0.1 V
1.2 V $\pm$ 0.1 V	15 pF	2 k $\Omega$	0.1 V
1.5 V $\pm$ 0.1 V	15 pF	2 k $\Omega$	0.1 V
1.8 V $\pm$ 0.15 V	30 pF	1 k $\Omega$	0.15 V
2.5 V $\pm$ 0.2 V	30 pF	500 $\Omega$	0.15 V



- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ , slew rate  $\geq$  1 V/ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .
  - H. All parameters and waveforms are not applicable to all devices.

**Figure 1. Load Circuit and Voltage Waveforms**

**PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74AUC32245GKER	NRND	LFBGA	GKE	96	1000	TBD	SNPB	Level-3-220C-168 HR
SN74AUC32245ZKER	ACTIVE	LFBGA	ZKE	96	1000	Green (RoHS & no Sb/Br)	SNAGCU	Level-3-260C-168 HR

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

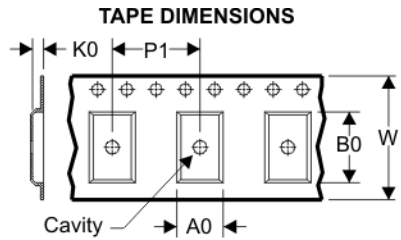
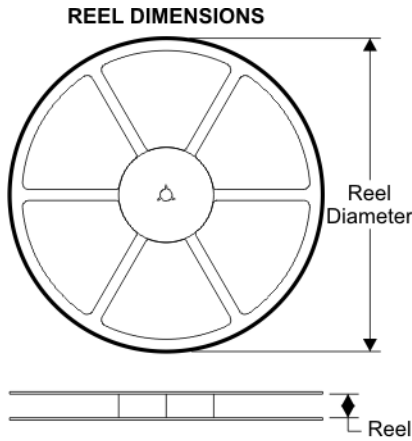
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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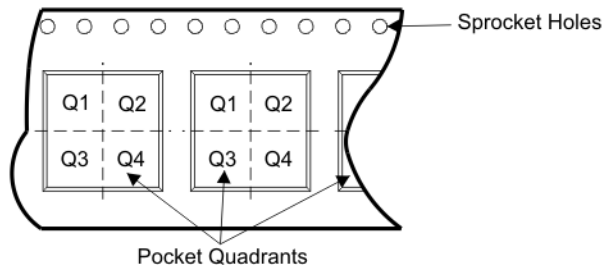
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**TAPE AND REEL BOX INFORMATION**



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

**QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE**



Device	Package	Pins	Site	Reel Diameter (mm)	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74AUC32245GKER	GKE	96	SITE 32	330	24	5.7	13.7	2.0	8	24	Q1
SN74AUC32245ZKER	ZKE	96	SITE 32	330	24	5.7	13.7	2.0	8	24	Q1



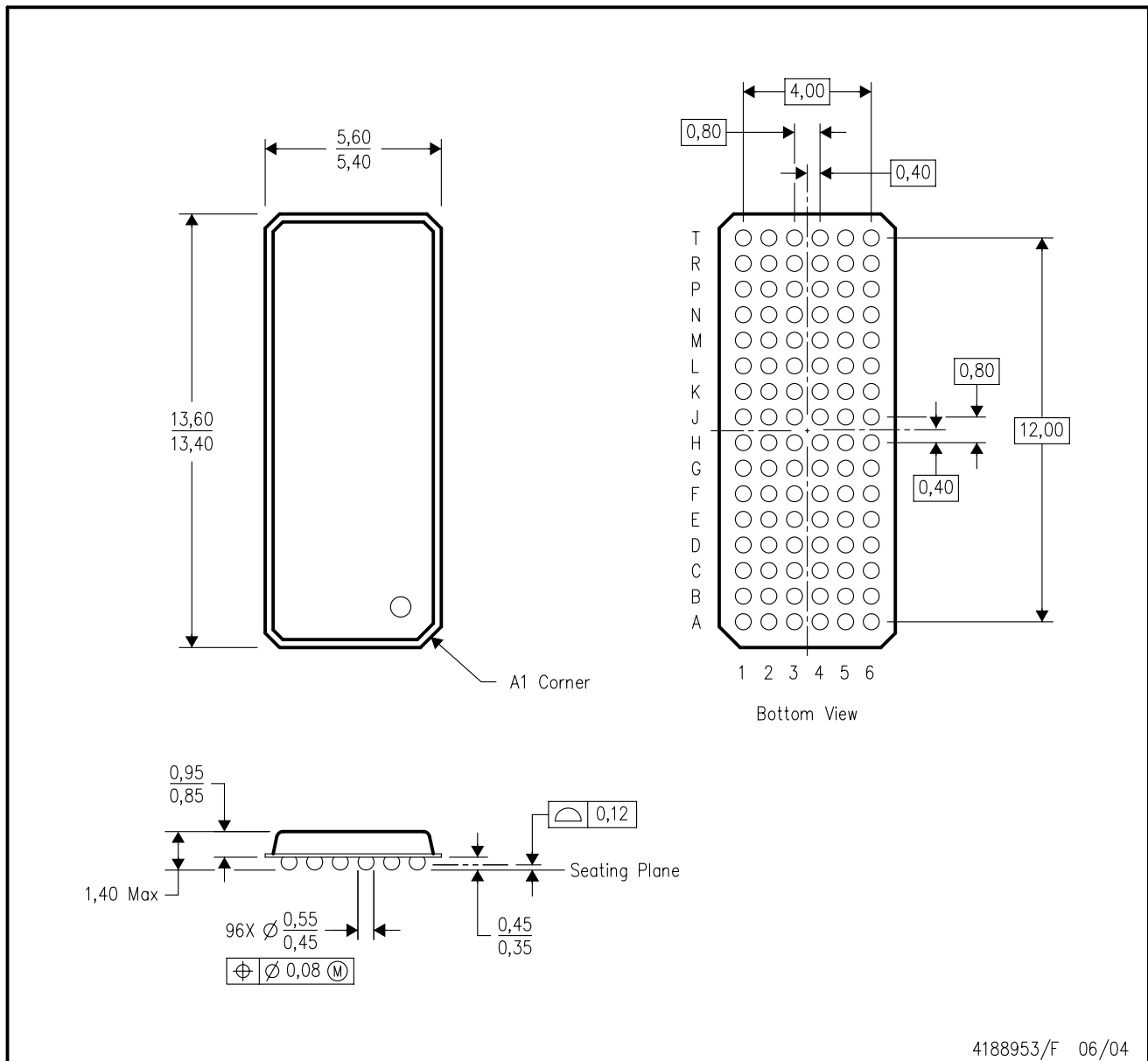
**TAPE AND REEL BOX DIMENSIONS**



Device	Package	Pins	Site	Length (mm)	Width (mm)	Height (mm)
SN74AUC32245GKER	GKE	96	SITE 32	346.0	346.0	41.0
SN74AUC32245ZKER	ZKE	96	SITE 32	346.0	346.0	41.0

GKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY

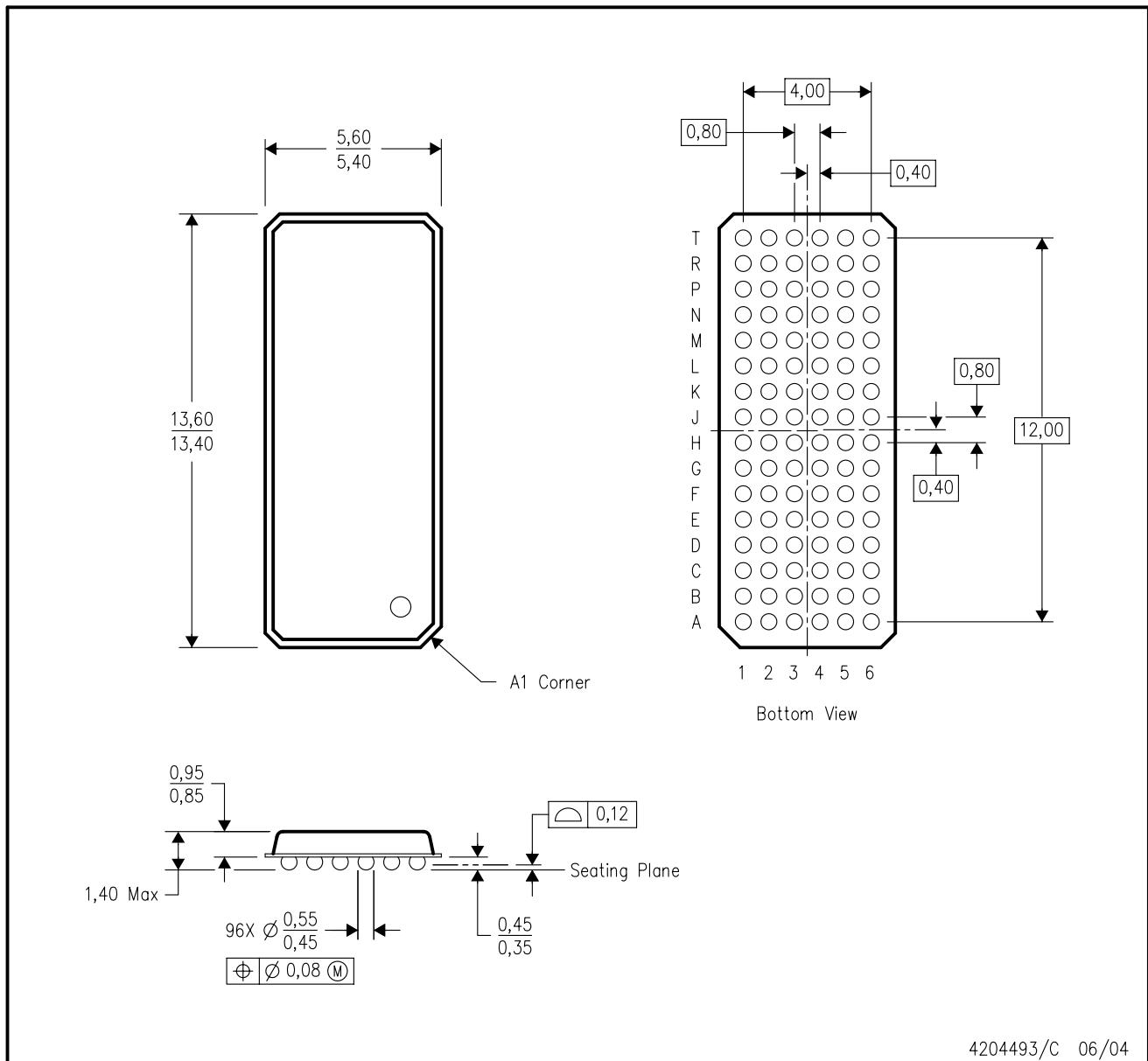


4188953/F 06/04

- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation CC.
  - D. This package is tin-lead (SnPb). Refer to the 96 ZKE package (drawing 4204493) for lead-free.

ZKE (R-PBGA-N96)

PLASTIC BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Falls within JEDEC MO-205 variation CC.
  - D. This package is lead-free. Refer to the 96 GKE package (drawing 4188953) for tin-lead (SnPb).

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Microcontrollers	<a href="http://microcontroller.ti.com">microcontroller.ti.com</a>	Security	<a href="http://www.ti.com/security">www.ti.com/security</a>
RFID	<a href="http://www.ti-rfid.com">www.ti-rfid.com</a>	Telephony	<a href="http://www.ti.com/telephony">www.ti.com/telephony</a>
Low Power Wireless	<a href="http://www.ti.com/lpw">www.ti.com/lpw</a>	Video & Imaging	<a href="http://www.ti.com/video">www.ti.com/video</a>
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